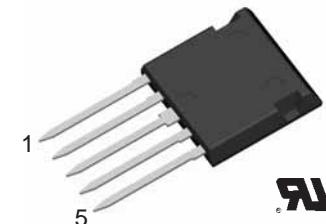
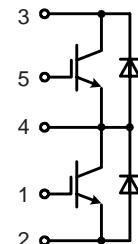


## NPT<sup>3</sup> IGBT phaseleg

in ISOPLUS i4-PAC<sup>TM</sup>

**I<sub>C25</sub>** = 50 A  
**V<sub>CES</sub>** = 1200 V  
**V<sub>CE(sat) typ.</sub>** = 2.0 V



### IGBTs

Symbol	Conditions	Maximum Ratings		
V <sub>CES</sub>	T <sub>VJ</sub> = 25°C to 150°C	1200		V
V <sub>GES</sub>		± 20		V
I <sub>C25</sub>	T <sub>C</sub> = 25°C	50	A	
I <sub>C90</sub>	T <sub>C</sub> = 90°C	32	A	
I <sub>CM</sub>	{ V <sub>GE</sub> = ±15 V; R <sub>G</sub> = 39 Ω; T <sub>VJ</sub> = 125°C V <sub>CEK</sub> RBSOA, Clamped inductive load; L = 100 μH }	50	A	
V <sub>CES</sub>		V <sub>CES</sub>		
t <sub>sc</sub>	V <sub>CE</sub> = 900V; V <sub>GE</sub> = ±15 V; R <sub>G</sub> = 39 Ω; T <sub>VJ</sub> = 125°C (SCSOA) non-repetitive	10	μs	
P <sub>tot</sub>	T <sub>C</sub> = 25°C	200		W

Symbol	Conditions	Characteristic Values		
		(T <sub>VJ</sub> = 25°C, unless otherwise specified)	min.	typ.
V <sub>CE(sat)</sub>	I <sub>C</sub> = 30 A; V <sub>GE</sub> = 15 V; T <sub>VJ</sub> = 25°C T <sub>VJ</sub> = 125°C	2.0 2.3	2.6	V

V <sub>GE(th)</sub>	I <sub>C</sub> = 1 mA; V <sub>GE</sub> = V <sub>CE</sub>	4.5		6.5	V
I <sub>CES</sub>	V <sub>CE</sub> = V <sub>CES</sub> ; V <sub>GE</sub> = 0 V; T <sub>VJ</sub> = 25°C T <sub>VJ</sub> = 125°C	0.4	0.4	mA	mA
I <sub>GES</sub>	V <sub>CE</sub> = 0 V; V <sub>GE</sub> = ± 20 V		200	nA	
t <sub>d(on)</sub>	{ Inductive load, T <sub>VJ</sub> = 125°C V <sub>CE</sub> = 600 V; I <sub>C</sub> = 30 A V <sub>GE</sub> = ±15 V; R <sub>G</sub> = 39 Ω }	85		ns	
t <sub>r</sub>		50		ns	
t <sub>d(off)</sub>		440		ns	
t <sub>f</sub>		50		ns	
E <sub>on</sub>		4.6		mJ	
E <sub>off</sub>		2.2		mJ	
C <sub>ies</sub>	V <sub>CE</sub> = 25 V; V <sub>GE</sub> = 0 V; f = 1 MHz	2		nF	
Q <sub>Gon</sub>	V <sub>CE</sub> = 600 V; V <sub>GE</sub> = 15 V; I <sub>C</sub> = 30 A	250		nC	
R <sub>thJC</sub>	with heatsink compound		0.6	K/W	
R <sub>thJH</sub>		1.2		K/W	

### Features

- NPT<sup>3</sup> IGBT
  - low saturation voltage
  - positive temperature coefficient for easy paralleling
  - fast switching
  - short tail current for optimized performance in resonant circuits
- HiPerFRED<sup>TM</sup> diode
  - fast reverse recovery
  - low operating forward voltage
  - low leakage current
- ISOPLUS i4-PAC<sup>TM</sup> package
  - isolated back surface
  - enlarged creepage towards heatsink
  - application friendly pinout
  - low inductive current path
  - high reliability
  - industry standard outline
  - UL registered, E 72873

### Applications

- single phaseleg
  - buck-boost chopper
- H bridge
  - power supplies
  - induction heating
  - four quadrant DC drives
  - controlled rectifier
- three phase bridge
  - AC drives
  - controlled rectifier

## Diodes

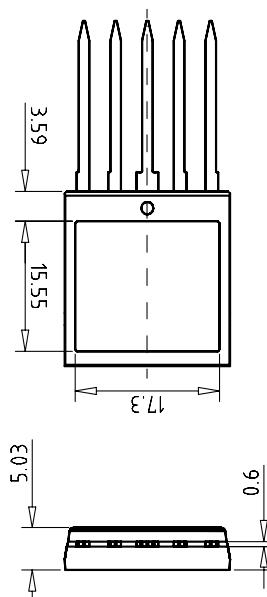
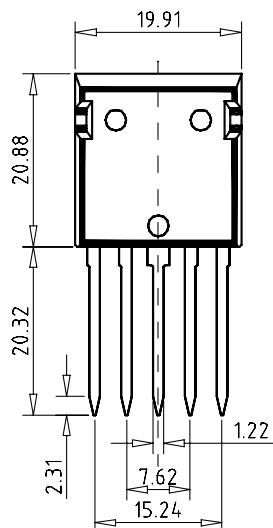
Symbol	Conditions	Maximum Ratings		
I <sub>F25</sub>	T <sub>C</sub> = 25°C	48	A	
I <sub>F90</sub>	T <sub>C</sub> = 90°C	25	A	

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
V <sub>F</sub>	I <sub>F</sub> = 30 A; T <sub>VI</sub> = 25°C T <sub>VJ</sub> = 125°C	2.4	2.8	V
		1.8		V
I <sub>RM</sub> t <sub>rr</sub> E <sub>rec(off)</sub>	I <sub>F</sub> = 30 A; di <sub>F</sub> /dt = -1100 A/μs; T <sub>VJ</sub> = 125°C V <sub>R</sub> = 600 V; V <sub>GE</sub> = 0 V	51		A
		180		ns
		1.8		mJ
R <sub>thJC</sub> R <sub>thJS</sub>	(per diode)	1.6	1.3	K/W
				K/W

## Component

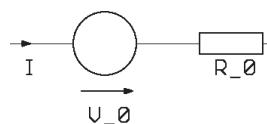
Symbol	Conditions	Maximum Ratings		
T <sub>VJ</sub>		-55...+150		°C
T <sub>stg</sub>		-55...+125		°C
V <sub>ISOL</sub>	I <sub>ISOL</sub> ≤ 1 mA; 50/60 Hz	2500		V~
F <sub>c</sub>	mounting force with clip	20...120		N

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
d <sub>s,d</sub> <sub>A</sub>	pin - pin	1.7		mm
d <sub>s,d</sub> <sub>A</sub>	pin - backside metal	5.5		mm
Weight		9		g



## Equivalent Circuits for Simulation

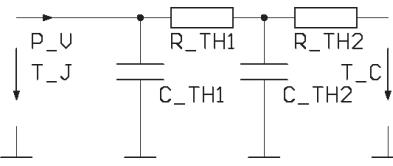
## Conduction



IGBT (typ. at V<sub>GE</sub> = 15 V; T<sub>J</sub> = 125°C)  
V<sub>θ</sub> = 0.95 V; R<sub>θ</sub> = 45 mΩ

Diode (typ. at T<sub>J</sub> = 125°C)  
V<sub>θ</sub> = 1.26 V; R<sub>θ</sub> = 15 mΩ

## Thermal Response



## IGBT

$$C_{th1} = 0.067 \text{ J/K}; R_{th1} = 0.108 \text{ K/W}$$

$$C_{th2} = 0.175 \text{ J/K}; R_{th2} = 0.491 \text{ K/W}$$

## Diode

$$C_{th1} = 0.039 \text{ J/K}; R_{th1} = 0.337 \text{ K/W}$$

$$C_{th2} = 0.090 \text{ J/K}; R_{th2} = 0.963 \text{ K/W}$$

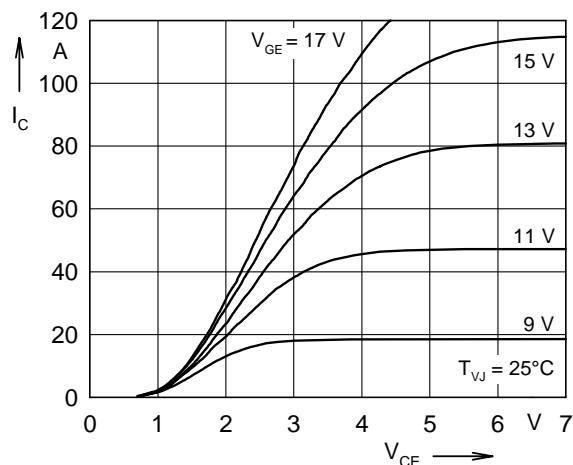


Fig. 1 Typ. output characteristics

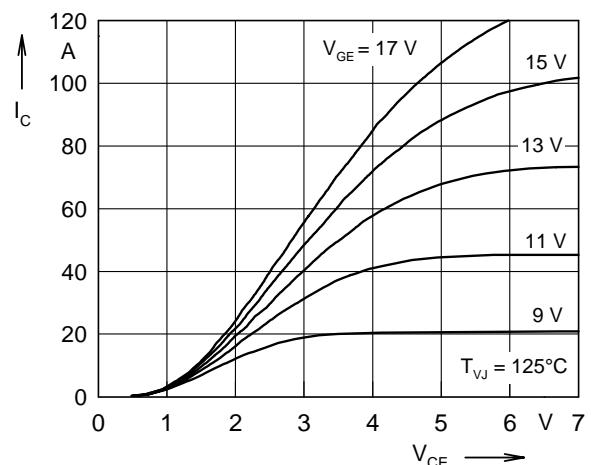


Fig. 2 Typ. output characteristics

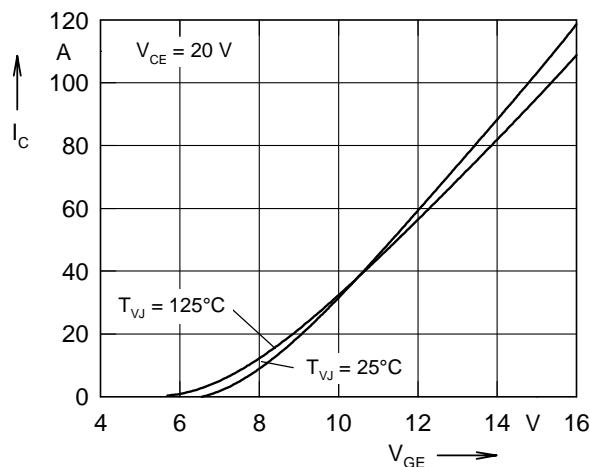


Fig. 3 Typ. transfer characteristics

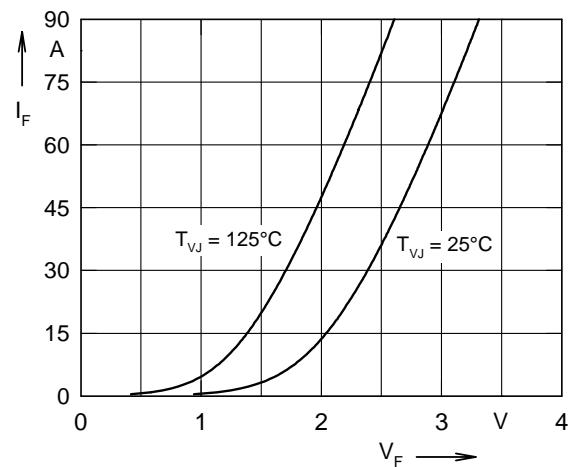


Fig. 4 Typ. forward characteristics of free wheeling diode

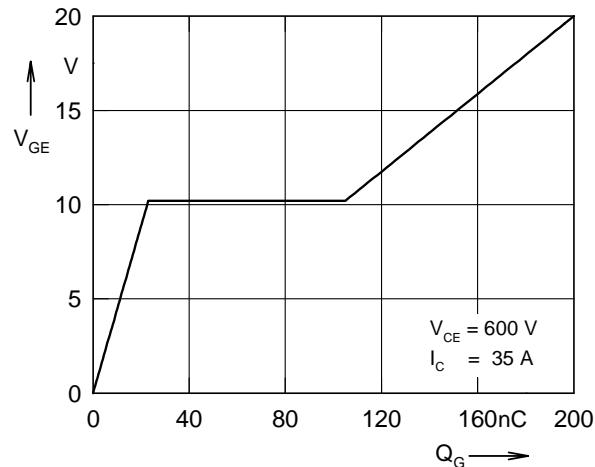


Fig. 5 Typ. turn on gate charge

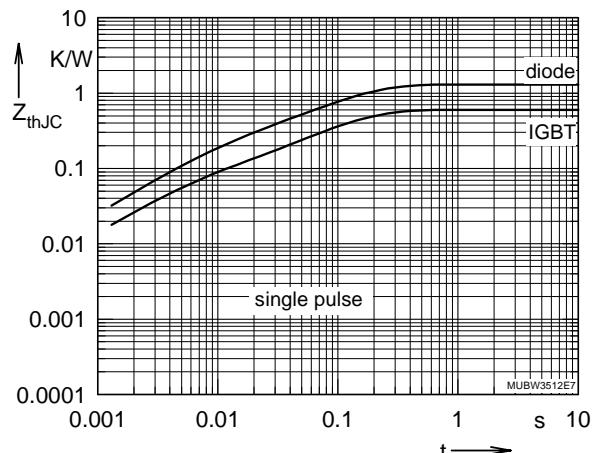


Fig. 6 Typ. transient thermal impedance

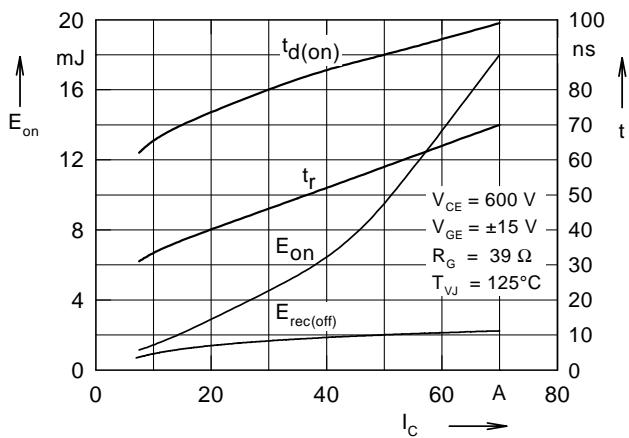


Fig. 7 Typ. turn on energy and switching times versus collector current

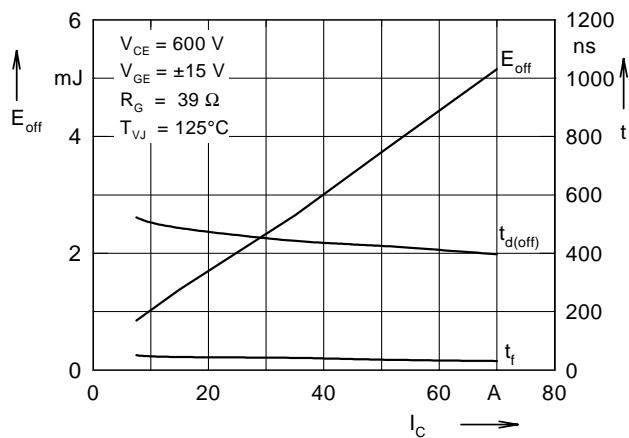


Fig. 8 Typ. turn off energy and switching times versus collector current

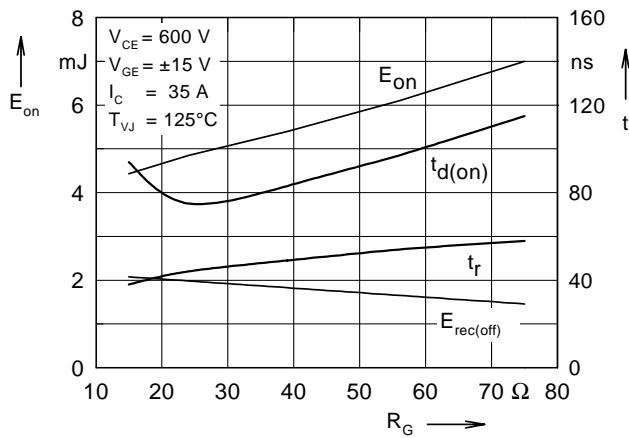


Fig. 9 Typ. turn on energy and switching times versus gate resistor

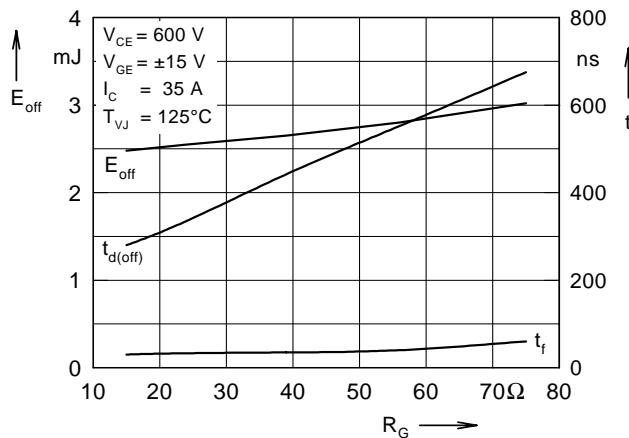


Fig. 10 Typ. turn off energy and switching times versus gate resistor

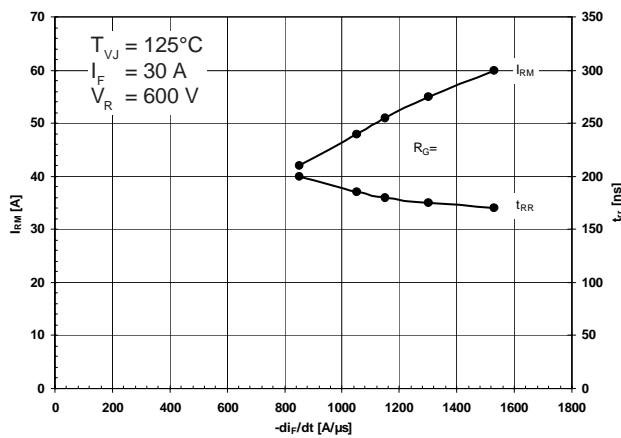


Fig. 11 Typ. turn off characteristics of free wheeling diode

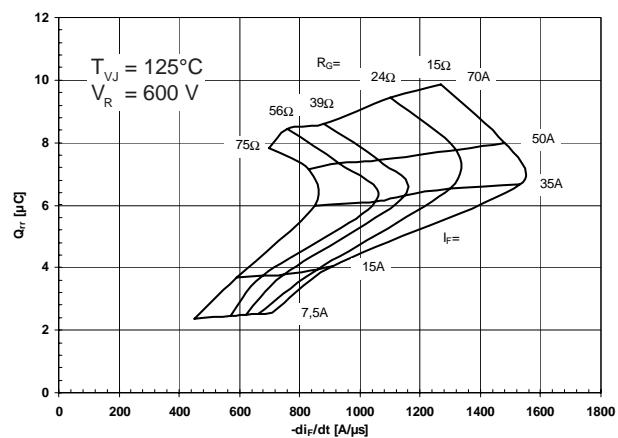


Fig. 12 Typ. turn off characteristics of free wheeling diode